

# MOS FIELD EFFECT TRANSISTOR 2SK3640

# SWITCHING N-CHANNEL POWER MOS FET

#### **DESCRIPTION**

The 2SK3640 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, and designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

#### ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3640-ZK	TO-252 (MP-3ZK)

#### **FEATURES**

· Low on-state resistance

 $R_{DS(on)1}$  = 21  $m\Omega$  MAX. (VGS = 10 V, ID = 9 A)

 $R_{DS(on)2} = 40 \text{ m}\Omega \text{ MAX.} (V_{GS} = 4.5 \text{ V}, I_D = 9 \text{ A})$ 

- Low Ciss: Ciss = 570 pF TYP.
- Built-in gate protection diode

(TO-252)



#### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^{\circ}C$ )

Drain to Source Voltage (Vgs = 0 V)	VDSS	30	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±16	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±19	Α
Drain Current (pulse) Note1	I <sub>D(pulse)</sub>	±76	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	20	W
Total Power Dissipation	P <sub>T2</sub>	1.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C
Single Avalanche Current Note2	las	10	Α
Single Avalanche Energy Note2	Eas	10	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

**2.** Starting T<sub>ch</sub> = 25°C, V<sub>DD</sub> = 15 V, R<sub>G</sub> = 25  $\Omega$ , L = 100  $\mu$ H, V<sub>GS</sub> = 20  $\rightarrow$  0 V

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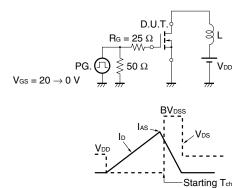


# **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

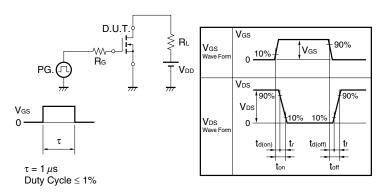
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate Leakage Current	Igss	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V			±10	μΑ
Gate Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5		2.5	V
Forward Transfer Admittance Note	<b>y</b> fs	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 9 A	3.7	7.4		S
Drain to Source On-state Resistance Note	R <sub>DS(on)1</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9 A		15	21	$m\Omega$
	R <sub>DS(on)2</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 9 A		24	40	$m\Omega$
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V		570		pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V		160		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		100		pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 9 A		7.7		ns
Rise Time	tr	V <sub>GS</sub> = 10 V		4.7		ns
Turn-off Delay Time	td(off)	$R_G$ = 10 $\Omega$		24		ns
Fall Time	<b>t</b> f			7		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 24 V		14		nC
Gate to Source Charge	Qgs	V <sub>GS</sub> = 10 V		2.4		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 19 A		4.3		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	I <sub>F</sub> = 19 A, V <sub>GS</sub> = 0 V		0.95		V
Reverse Recovery Time	<b>t</b> rr	I <sub>F</sub> = 19 A, V <sub>GS</sub> = 0 V		21		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		12		nC

**Note** Pulsed: PW  $\leq$  350  $\mu$ s, Duty Cycle  $\leq$  2%

#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**



#### **TEST CIRCUIT 2 SWITCHING TIME**

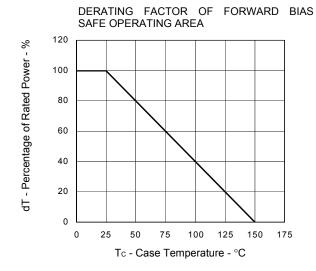


# **TEST CIRCUIT 3 GATE CHARGE**

$$\begin{array}{c|c} & D.U.T. \\ \hline I_G = 2 & \text{mA} \\ \hline & & \\ \hline & &$$

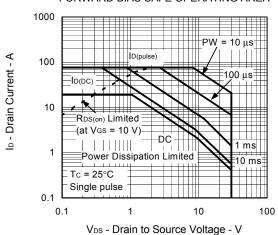


# TYPICAL CHARACTERISTICS (TA = 25°C)

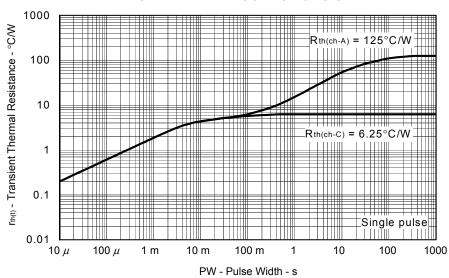


#### TOTAL POWER DISSIPATION vs. CASE TEMPERATURE P<sub>T</sub> - Total Power Dissipation - W Tc - Case Temperature - °C

#### FORWARD BIAS SAFE OPERATING AREA



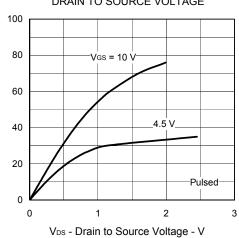
#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



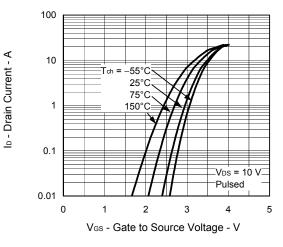
lo - Drain Current - A

VGS(off) - Gate Cut-off Voltage - V

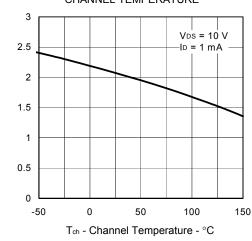
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE 100



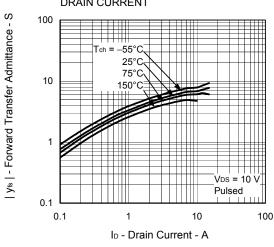
FORWARD TRANSFER CHARACTERISTICS



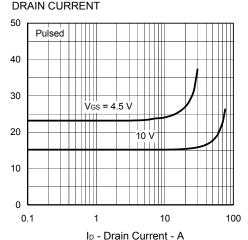
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



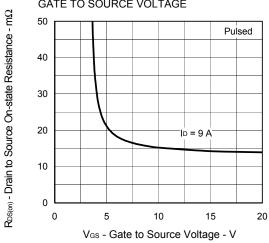
FORWARD TRANSFER ADMITTANCE vs. **DRAIN CURRENT** 



DRAIN TO SOURCE ON-STATE RESISTANCE vs. **DRAIN CURRENT** 



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

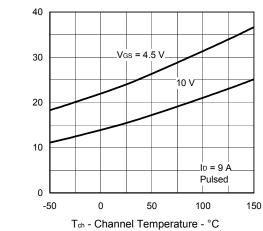


RDS(m) - Drain to Source On-state Resistance - mΩ

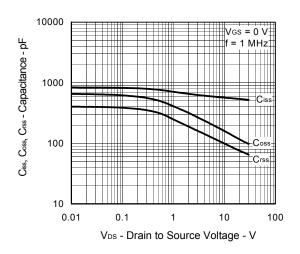
R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

IF - Diode Forward Current - A

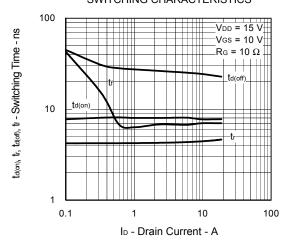
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



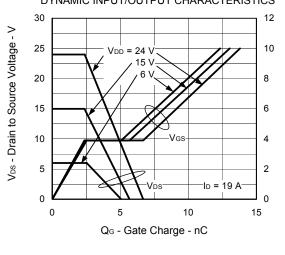
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



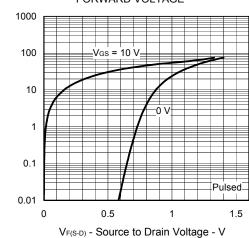
SWITCHING CHARACTERISTICS



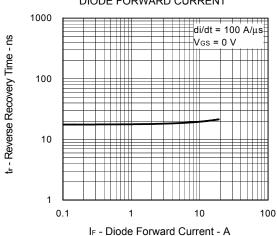
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

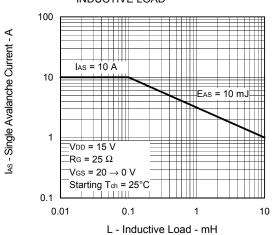


REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

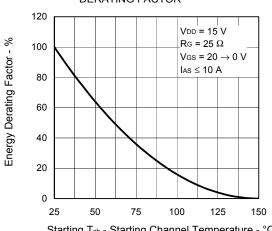


Ves - Gate to Source Voltage - V

#### SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



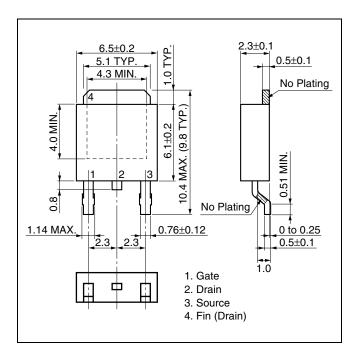
#### SINGLE AVALANCHE ENERGY **DERATING FACTOR**



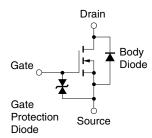
Starting  $T_{\text{ch}}$  - Starting Channel Temperature - °C

# **★ PACKAGE DRAWING (Unit: mm)**

# TO-252 (MP-3ZK)



# **EQUIVALENT CIRCUIT**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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